Kang-Yi Lin

List of Publications by Year
in descending order

10 papers	221 citations	1307366 7 h-index	1372474 10 g-index
10 all docs	10 docs citations	10 times ranked	417 citing authors

#	Article	IF	Citations
1	Significance of plasma-photoresist interactions for atomic layer etching processes with extreme ultraviolet photoresist. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	4
2	Selective atomic layer etching of HfO2 over silicon by precursor and substrate-dependent selective deposition. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	16
3	Assessment of the Effects of Surface Potential on the Kinetics of HEK293T Cell Adhesion Behavior Using a Quartz Crystal Microbalance with Dissipation Monitoring. Journal of Physical Chemistry C, 2018, 122, 694-704.	1.5	9
4	Achieving ultrahigh etching selectivity of SiO2 over Si3N4 and Si in atomic layer etching by exploiting chemistry of complex hydrofluorocarbon precursors. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2018, 36, .	0.9	40
5	Effect of Surface Potential on the Adhesion Behavior of NIH3T3 Cells Revealed by Quartz Crystal Microbalance with Dissipation Monitoring (QCM-D). Journal of Physical Chemistry C, 2017, 121, 533-541.	1.5	32
6	Improvement of the gas cluster ion beam-(GCIB)-based molecular secondary ion mass spectroscopy (SIMS) depth profile with O₂⁺ cosputtering. Analyst, The, 2016, 141, 2523-2533.	1.7	9
7	Effect of Surface Potential on Extracellular Matrix Protein Adsorption. Langmuir, 2014, 30, 10328-10335.	1.6	45
8	Effect of Surface Potential on NIH3T3 Cell Adhesion and Proliferation. Journal of Physical Chemistry C, 2014, 118, 14464-14470.	1.5	57
9	Enhancing the Sensitivity of Molecular Secondary Ion Mass Spectrometry with C₆₀⁺-O₂⁺ Cosputtering. Analytical Chemistry, 2013, 85, 3781-3788.	3.2	7
10	Ag Electromigration Against Electron Flow in Sn5Ag/Cu Solder Bump. Electrochemical and Solid-State Letters, 2009, 12, H445.	2.2	2